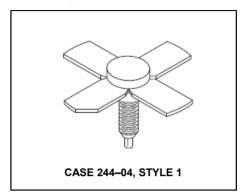


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Designed primarily for wideband large-signal driver and predriver amplifier stages in 200-500 MHz frequency range.

- Guaranteed performance at 400 MHz, 28 Vdc Output power = 10 W
  - Power gain = 12 dB min. Efficiency = 50% min.
- 100% tested for load mismatch at all phase angles with 30:1 VSWR
- Gold metallization system for high reliability
- Computer-controlled wirebonding gives consistent input Impedance

### **Product Image**



#### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V <sub>CEO</sub>	33	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	60	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	4.0	Vdc
Collector Current — Continuous — Peak	I <sub>C</sub>	1.1 1.5	Adc
Total Device Dissipation @ T <sub>A</sub> = 25°C (1) Derate above 25°C	P <sub>D</sub>	27 160	Watts mW/°C

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	R <sub>0JC</sub>	6.4	°C/W

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	•			•
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 20 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	33	_	_	Vdc
Collector–Emitter Breakdown Voltage (I <sub>C</sub> = 20 mAdc, V <sub>BE</sub> = 0)	V <sub>(BR)</sub> CES	60	_	_	Vdc
Collector–Base Breakdown Voltage (I <sub>C</sub> = 20 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)</sub> CBO	60	_	_	Vdc
Emitter–Base Breakdown Voltage (I <sub>E</sub> = 2.0 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	4.0	_	_	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 30 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>	_	_	1.0	mAdc
ON CHARACTERISTICS	•	•	•	•	
DC Current Gain	h <sub>FE</sub>	20	_	80	_

DC Current Gain	h <sub>FE</sub>	20	_	80	_
(I <sub>C</sub> = 500 mA, V <sub>CE</sub> = 5.0 Vdc)					

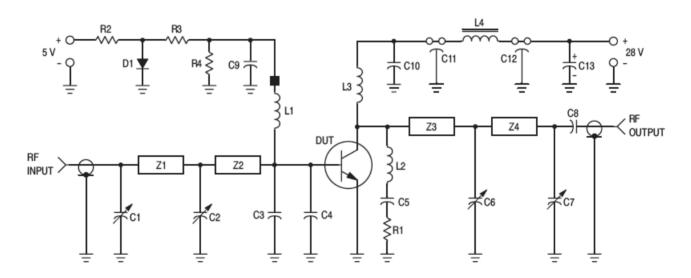
NOTE: 1. This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF amplifier.



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#### ELECTRICAL CHARACTERISTICS — continued (T<sub>C</sub> = 25°C unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
DYNAMIC CHARACTERISTICS	•	•		•	
Output Capacitance (V <sub>CB</sub> = 28 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	_	10	12	pF
FUNCTIONAL TESTS (Figure 1)		•			
Common–Emitter Amplifier Power Gain (V <sub>CC</sub> = 28 Vdc, P <sub>out</sub> = 10 W, f = 400 MHz)	G <sub>PE</sub>	12	13	_	dB
Collector Efficiency (V <sub>CC</sub> = 28 Vdc, P <sub>out</sub> = 10 W, f = 400 MHz)	η	50	60	_	%
Load Mismatch (V <sub>CC</sub> = 28 Vdc, P <sub>out</sub> = 10 W, f = 400 MHz, VSWR = 30:1 all phase angles)	Ψ	No	Degradation	in Output Pow	er



C1, C2, C3 — 1.0-20 pF Johanson Trimmer (JMC 5501)

C3, C4 - 47 pF ATC Chip Capacitor

C5, C10 — 0.1 µF Erie Redcap

C7 — 0.5-10 pF Johanson Trimmer (JMC 5201)

C8 - 0.018 µF Vitramon Chip Capacitor

C9 - 200 pF UNELCO Capacitor

C11, C12 - 680 pF Feedthru

C13 - 1.0 µF, 50 Volt Tantalum Capacitor

D1 - 1N4001

L1 — 0.33 μH Molded Choke with Ferroxcube Bead (Ferroxcube 56–590–65/4B) on Ground End of Coil

L2 - 4 Turns #20 Enamel, 1/8" ID

L3 — 6 Turns #20 Enamel. 1/4" ID

L4 — Ferroxcube VK200–19/4B

R1 — 5.1 Ω, 1/4 Watt

R2 — 120 Ω, 1.0 Watt

R3 — 20 Ω, 1/2 Watt

R4 - 47 Ω, 1/2 Watt

Z1 - Microstrip 0.1" W x 1.35" L

Z2 - Microstrip 0.1" W x 0.55" L

Z3 — Microstrip 0.1" W x 0.8" L

Z4 — Microstrip 0.1" W x 1.75" L

Board — Glass Teflon,  $\varepsilon_R$  = 2.56, t = 0.062"

Input/Output Connectors — Type N

Figure 1. 400 MHz Test Circuit Schematic



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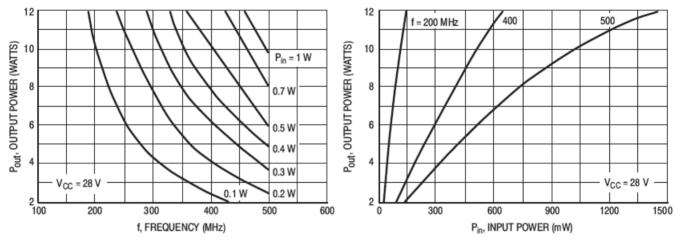


Figure 2. Output Power versus Frequency

Figure 3. Output Power versus Input Power

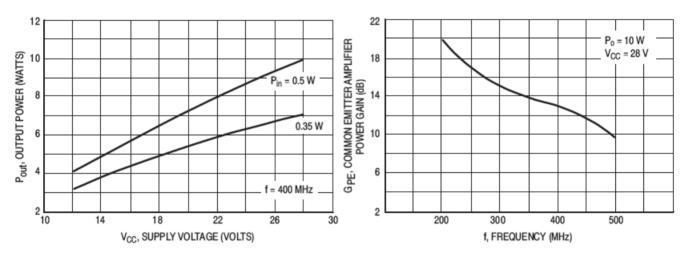
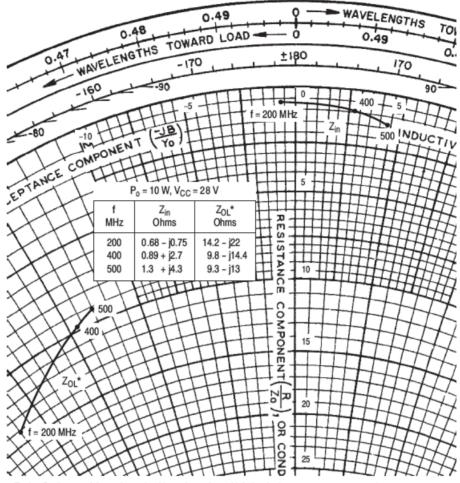


Figure 4. Output Power versus Supply Voltage

Figure 5. Power Gain versus Frequency



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Z<sub>OL</sub>\* = Conjugate of the optimum load impedance into which the device output operates at a given output power, voltage and frequency.

Figure 6. Series Equivalent Impedance



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#### PACKAGE DIMENSIONS

